

Title (en)

Radiation curable resin composition and rapid prototyping process using the same

Title (de)

Strahlungshärtbare Harzzusammensetzung und rapides Prototyping-Verfahren damit

Title (fr)

Composition de résine durcissable par rayonnement et processus de prototypage rapide l'utilisant

Publication

EP 2466378 B1 20140108 (EN)

Application

EP 12154838 A 20030501

Priority

- EP 03721169 A 20030501
- US 37723902 P 20020503

Abstract (en)

[origin: WO03093901A1] The invention relates to a radiation curable composition comprising relative to the total weight of the composition (A) 0-29 wt % of a cationically curable component having a linking aliphatic ester group, (B) 10-85 wt % of an epoxygroup containing component other than A, (C) 1-50 wt % of an oxetanegroup containing component, (D) 1-25 wt % of a multifunctional acrylate and a radical photoinitiator and a cationic photoinitiator.

IPC 8 full level

C08G 65/18 (2006.01); **G03F 7/00** (2006.01); **B29C 35/04** (2006.01); **C08F 283/02** (2006.01); **C08F 283/06** (2006.01); **C08F 283/10** (2006.01); **C08G 59/17** (2006.01); **G03C 1/73** (2006.01); **G03F 7/027** (2006.01); **G03F 7/038** (2006.01)

CPC (source: EP KR US)

B29C 64/106 (2017.07 - EP); **B33Y 70/00** (2014.12 - EP KR US); **C08F 283/06** (2013.01 - EP US); **C08F 283/10** (2013.01 - EP US); **C08F 290/06** (2013.01 - EP US); **C08G 59/68** (2013.01 - EP US); **C08G 65/18** (2013.01 - EP US); **G03F 7/0037** (2013.01 - EP US); **G03F 7/027** (2013.01 - EP US); **G03F 7/038** (2013.01 - EP KR US); **B33Y 10/00** (2014.12 - EP US)

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 03093901 A1 20031113; AU 2003224516 A1 20031117; CN 100576069 C 20091230; CN 101706639 A 20100512; CN 1650231 A 20050803; EP 1502155 A1 20050202; EP 1502155 B1 20130130; EP 2466378 A2 20120620; EP 2466378 A3 20120905; EP 2466378 B1 20140108; ES 2405107 T3 20130530; HK 1080554 A1 20060428; JP 2005529200 A 20050929; JP 2010189641 A 20100902; JP 5656419 B2 20150121; KR 101176747 B1 20120823; KR 20050007372 A 20050117; KR 20110051258 A 20110517; KR 20120086737 A 20120803; US 2004142274 A1 20040722; US 2007154840 A1 20070705; US 2008064780 A1 20080313; US 7183040 B2 20070227

DOCDB simple family (application)

NL 0300320 W 20030501; AU 2003224516 A 20030501; CN 03810052 A 20030501; CN 200910224789 A 20030501; EP 03721169 A 20030501; EP 12154838 A 20030501; ES 03721169 T 20030501; HK 06100453 A 20060111; JP 2004502060 A 20030501; JP 2010036379 A 20100222; KR 20047017652 A 20030501; KR 20117006984 A 20030501; KR 20127016516 A 20030501; US 62315303 A 20030721; US 65045307 A 20070108; US 97987807 A 20071109